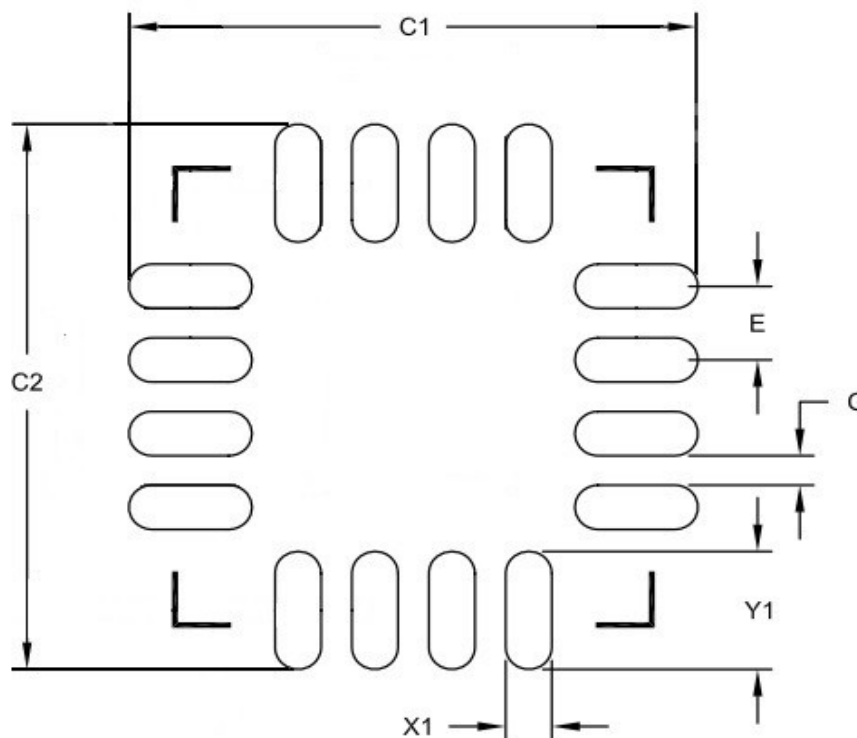


LGA16 9.2x9.2mm 1.8mm - stencil

		Units	MILLIMETERS		
Dimension Limit			MIN	NOM	MAX
Contact Pitch	E			1.80	
Contact Pad Spacing	C1,C2			9.54	
Contact Pad Width	X1			0.90	
Contact Pad Length	Y1			0.60	
Distance Between Pads	G			0.90	

Top View (SMD Footprint)



Stencil dimensions: 38mm x 28mm

Thickness: 100-127 μ m

Material: stainless steel or nickel silver

Manufacturing processes: lasering or chemical etching

Datasheet rev.: 1.04